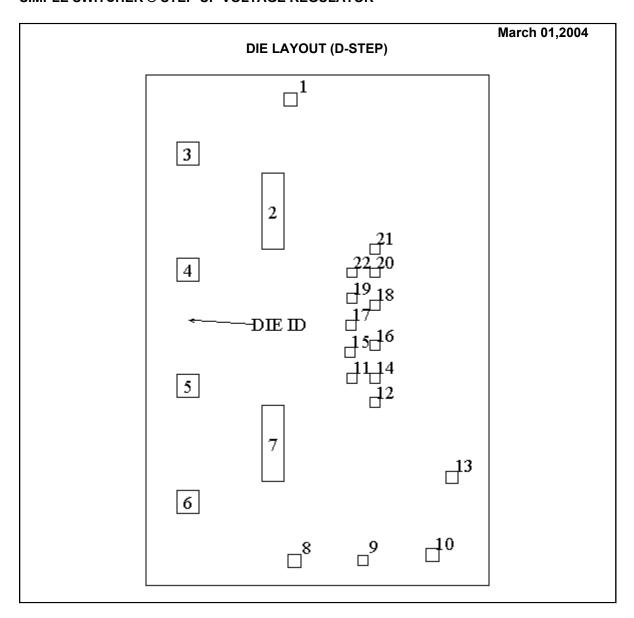


LM2577-ADJ MDC MWC SIMPLE SWITCHER ® STEP-UP VOLTAGE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information			
Physical Die Identification	LM1577D	Bond Pad Opening Size (min)	80μm x 80μm		
Die Step	D	Bond Pad Metalization	ALUMINUM		
Physi	Physical Attributes		VOM NITRIDE		
Wafer Diameter	150mm	Back Side Metal	BARE BACK		
Die Size (Drawn)	2743μm x 4089μm 108.0mils x 161.0mils	Back Side Connection	GND		
Thickness	406μm Nominal				
Min Pitch	186µm Nominal				

Special Assembly Requirements:	
Note: Actual die size is rounded to the nearest micron.	



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	Die Bond Pad	Coordinate	Locations (D	-Step)		
(Referenced	to die center, coordi	nates in μm) N	C = No Conne	ction, N.U.	= Not	Used
SIGNAL	PAD#	X/Y COORDINATES PAD S				IZE
NAME	NUMBER	X	Υ	X		Y
VIN	1	-215	1851	102	Χ	102
SWITCH	2	-355	951	180	Χ	608
GND	3	-1039	1416	180	Χ	180
GND	4	-1039	486	180	Χ	180
GND	5	-1039	-444	180	Χ	180
GND	6	-1039	-1374	180	Χ	180
SWITCH	7	-355	-909	180	Χ	608
COMP	8	-187	-1851	102	Χ	102
NC	9	362	-1843	80	X	80
FB	10	922	-1803	102	Χ	102
NC	11	276	-381	80	X	80
NC	12	462	-581	80	X	80
GND	13	1078	-1178	102	Χ	102
NC	14	462	-381	80	X	80
NC	15	263	-174	80	X	80
NC	16	462	-124	80	X	80
NC	17	269	40	80	X	80
NC	18	462	204	80	X	80
NC	19	275	254	80	X	80
NC	20	462	461	80	X	80
NC	21	462	652	80	X	80
NC	22	275	461	80	X	80

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